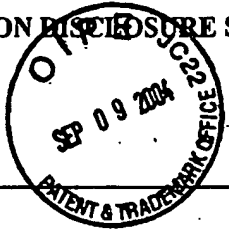
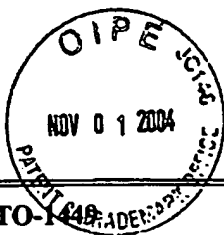


FORM PTO-1449				ATTY DOCKET NO.		SERIAL NO.	
INFORMATION DISCLOSURE STATEMENT				51565		10/696,552	
				APPLICANT(S): Seita et al.			
				FILING DATE: October 29, 2003		ART UNIT: 1753	
UNITED STATES PATENT DOCUMENTS							
EXAM. INITIAL		DOCUMENT NUMBER	DATE	NAME	CLASS	SUB CLASS	FIL. DATE IF APPR
FOREIGN PATENT DOCUMENTS							
		DOCUMENT NUMBER	DATE	COUNTRY	CLASS	SUB CLASS	TRAN YES/NO
<i>m</i>	BA	WO 01/38604 A1	05/31/2001	International			YES Abstract Only
OTHER DOCUMENTS (INCLUDING AUTHOR, TITLE, DATE, PERTINENT PAGES, ETC.)							
<i>m</i>	BA	Patent Abstracts of Japan, Publication No. 2001-214278 (08/07/2001); <a href="http://www19.ipdl.jpo.go.jp/PA1//result/detail/main/wAAA5vaOCTDA413214278P1.htm">http://www19.ipdl.jpo.go.jp/PA1//result/detail/main/wAAA5vaOCTDA413214278P1.htm</a> .					
Examiner:				Date: 9/27/05			



Sheet 1 of 1

FORM PTO-1449 INFORMATION DISCLOSURE STATEMENT				ATTY DOCKET NO. 51565		SERIAL NO. 10/696,552	
				APPLICANT(S): Seita et al.			
				FILING DATE: 10/29/2003		ART UNIT: 1753	
UNITED STATES PATENT DOCUMENTS							
EXAM. INITIAL		DOCUMENT NUMBER	DATE	NAME	CLASS	SUB CLASS	FIL. DATE IF APPR
FOREIGN PATENT DOCUMENTS							
		DOCUMENT NUMBER	DATE	COUNTRY	CLASS	SUB CLASS	TRAN SLATION/NO
<i>ML</i>	AA	0 251 302 A	01/07/1988	Europe			
OTHER DOCUMENTS (INCLUDING AUTHOR, TITLE, DATE, PERTINENT PAGES, ETC.)							
<i>ML</i>	BA	Database CA Online; Chemical Abstracts Service, Columbus, Ohio; Seita et al.; "Accelerator solution for direct plating and method for direct plating using same"; retrieved from STN Database accession no. 135:11520 CA XP002235694 & JP 2001 214278 A (LeaRonol Japan Inc., Japan); 7 August 2001.					
<i>ML</i>	BB	Patent Abstracts of Japan; Vol. 017, No. 554 (C-1118), 6 October 1993 & JP 05 156459 A (Hitachi Chem. Co. Ltd.; Others: 01), 22 June 1993.					
<i>ML</i>	BC	MicroPatent Worldwide PatSearch; JP 2002-348673 (04/12/2002); "Electroless Copper Plating Method Without Using Formaldehyde, and Electroless Copper Plating Solution Therefor"; LeaRonol Japan Inc.; Abstract.					
Examiner: <i>LaVille</i>				Date: <i>9/27/05</i>			